



0804MC

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8-Pin TO-3 Socket

FEATURES

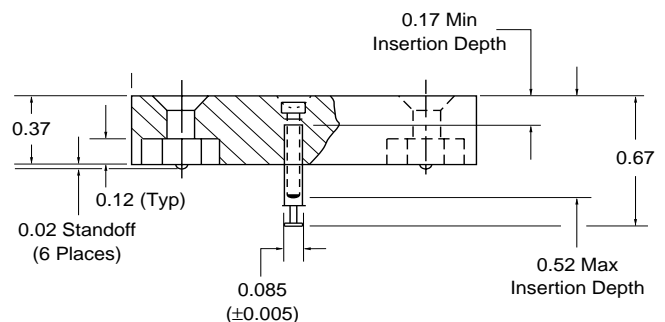
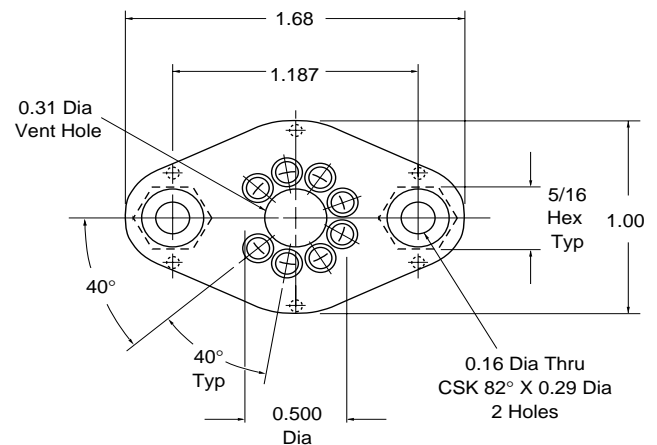
- LOW CONTACT RESISTANCE
- CLOSED CONTACT ENDS
- GOLD-PLATED INNER CONTACTS
- -55°C TO +150°C TEMPERATURE RANGE

DESCRIPTION

The 0804MC is a high quality socket designed for use with Burr-Brown's 8-pin TO-3 type products such as the OPA541 and OPA512.

Although not required for use with these products, the 0804MC socket makes interchanging parts easy, especially during design and testing. Its rugged inner contacts provide positive insertion and low contact resistance. Closed contact ends prevent solder and flux contamination of the internal contacts.

The socket body is molded of glass-filled polyester and incorporates counter-sunk mounting holes and hex-nut retaining feature. It accommodates a variety of mounting hardware and mechanical designs.



Contact Resistance: 0.02Ω Typ

Outer Contact: Brass
200μ inch Tin over 100μ inch Nickel Plate

Inner Contact: BeCu
30μ inch Gold over 50μ inch Nickel Plate

Socket Body: Glass-Filled Polyester, 94 V-0 rating

Operating Temperature Range: -55°C to +150°C

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